

Property	DOWSIL™ TC-2030 Adhesive	DOWSIL™ TC-2035 Adhesive
Product description	Silicone adhesive delivering superior thermal management for standard and advanced automotive PCB system modules	Silicone adhesive delivering advanced thermal management suitable for next-generation automotive PCB system applications
Form	Two-part, heat cure	Two-part, heat cure
Color after mix	Gray	Reddish brown
Mix ratio	1:1	1:1
Viscosity, Part A	250 Pa-s	130 Pa-s
Viscosity, Part B	200 Pa-s	130 Pa-s
Viscosity, mixed	220 Pa-s	130 Pa-s
Density (cured)	2.90 g/cm <sup>3</sup>	3.0 g/cm <sup>3</sup>
Viscosity after 4 hours of working time @ 25°C	230 Pa-s	116 Pa-s
Tensile strength	4.7 MPa	3.6 MPa
Heat cure time	60 minutes at 130°C	30 minutes at 125°C; 10 minutes at 150°C
Elongation	0,5	0,43
Durometer, Shore A (JIS)	92	95
Unprimed adhesion (lap shear strength Al/Al)	2.7 MPa	3.1 MPa
Thermal conductivity	2.7 W/mK	3.3 W/mK
Minimum BLT	130 µm	50 µm
Thermal resistivity at minimum BLT	0.8°C/W	0.25°C/W
Thermal resistivity at 150 µm BLT	0.8°C/W	0.59°C/W
Volume resistivity	4.3 E+15 ohm*cm	1.3 E+16 ohm*cm
Dielectric strength	21 kV/mm	21 kV/mm
Static mixer	MS 8-19	MS 8-19
Maximum speed	0.2 ml/sec for 1 ml	0.2 ml/sec for 2 ml
Interfacial contact optimization	Vacuum bonding	Vacuum bonding
Packaging	20 l pail, 6 oz cartridges	20 l pail, 6 oz cartridges